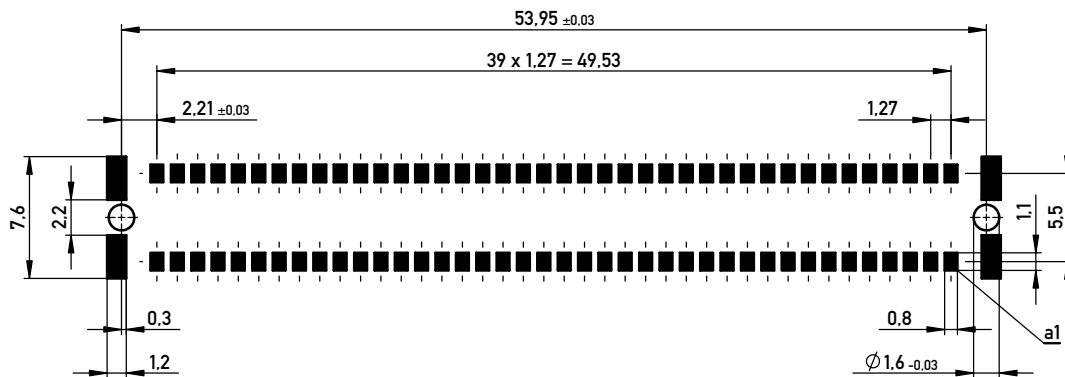


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT



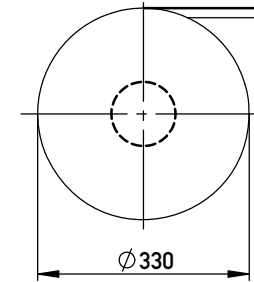
Anforderungsstufe 1  
Performance Level 1

Kontaktbereich vergoldet  
Mating Area gold plating

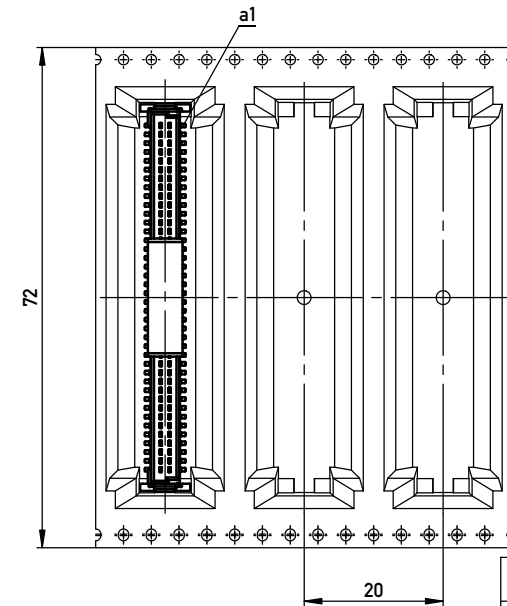
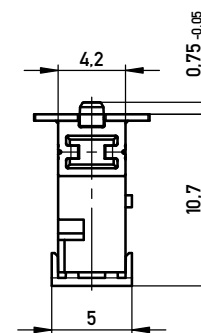
Anschlussbereich verzinkt 4-6 µm  
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
Coplanarity Area of Termination ≤ 0,1 mm

Verpackt im Gurt nach DIN IEC 60286-3  
Tape on Reel Packaging according to DIN IEC 60286-3  
Verpackungseinheit: 250 Stück  
Packaging unit: 250 pcs



Abspulrichtung - Reel off Direction



BA 8-23 - hohe Bauhöhe  
type 8-23 - High Profile

|   |  |                          |  |               |
|---|--|--------------------------|--|---------------|
| Information:  | Tolerances   | <br>All Dimensions in mm | Scale  | 3:1           |
|   | All rights reserved.<br>Only for Information.<br>To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using. |                          | Designation<br><b>Messrl. SMC-Q 80-SMD-BA8-23</b><br><i>Male SMC-Q 80-SMD-type8-23</i> |               |
| Subject to modification without prior notice.<br>Drawing will not be updated. |  | www.ERNI.com             |  | <b>234210</b> |
| e   | 26.06.2015   | Class                    |  | SMCQ          |
| Index   | Date   |                          |  | I<br>A3       |

Copyright by ERNI GmbH. Proprietary notice pursuant to ISO 9006 to be observed.